

# MOSFET – N-Channel, POWERTRENCH®

40 V, 7.6 A, 29 mΩ

## FDS8449, FDS8449-G

### General Description

These N-Channel MOSFETs are produced using onsemi's advanced POWERTRENCH process that has been especially tailored to minimize on-state resistance and yet maintain superior switching performance.

### Features

- 7.6 A, 40 V  $R_{DS(on)} = 29\text{ m}\Omega @ V_{GS} = 10\text{ V}$   
 $R_{DS(on)} = 36\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- High Power Handling Capability in a Widely Used Surface Mount Package
- Pb-Free, Halide Free and RoHS Compliant

### ABSOLUTE MAXIMUM RATINGS

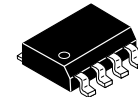
$T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain to Source Voltage	40	V
$V_{GSS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous (Note 1a) – Pulsed	7.6 50	A
$P_D$	Power Dissipation for Single Operation (Note 1a) (Note 1b)	2.5 1	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	$-55$ to $+150$	$^\circ\text{C}$

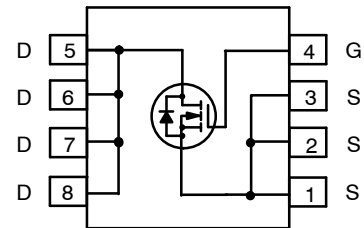
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS

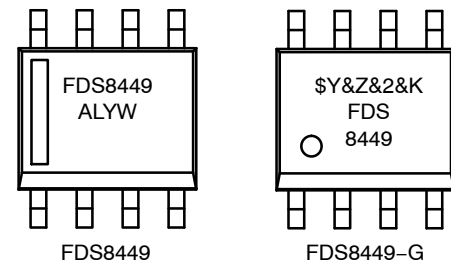
Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1b)	125	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Note 1)	25	$^\circ\text{C/W}$



SOIC8  
CASE 751EB



### MARKING DIAGRAM



- FDS8449 = Specific Device Code  
A = Assembly Site  
L = Wafer Lot Number  
YW = Assembly Start Week  
\$Y = onsemi Logo  
&Z = Assembly Plant Code  
&2 = 2-Digit Code Format  
&K = 2-Digits Lot Run Traceability Code

### ORDERING INFORMATION

Device	Package	Shipping†
FDS8449	SOIC8 (Pb-Free/ Halide Free)	2500 / Tape & Reel
FDS8449-G	SOIC8 (Pb-Free/ Halide Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

# FDS8449, FDS8449-G

**ELECTRICAL CHARACTERISTICS**  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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## DRAIN-SOURCE AVALANCHE RATINGS (Note 3)

$E_{AS}$	Drain to Source Avalanche Energy	$V_{DD} = 40\text{ V}, I_D = 7.3\text{ A}, L = 1\text{ mH}$	-	-	27	mJ
$I_{AS}$	Drain to Source Avalanche Current		-	7.3	-	A

## OFF CHARACTERISTICS

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\ \mu\text{A}, V_{GS} = 0\text{ V}$	40	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	34	-	mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 32\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 100$	nA

## ON CHARACTERISTICS (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1	1.9	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	-5	-	mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain to Source On-Resistance	$I_D = 7.6\text{ A}, V_{GS} = 10\text{ V}$ ,	-	21	29	m $\Omega$
		$I_D = 6.8\text{ A}, V_{GS} = 4.5\text{ V}$	-	26	36	
		$I_D = 7.6\text{ A}, V_{GS} = 10\text{ V}$ , $T_J = 125^\circ\text{C}$	-	29	43	
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{ V}, I_D = 7.6\text{ A}$	-	21	-	S

## DYNAMIC CHARACTERISTICS

$C_{iss}$	Input Capacitance	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}$ , $f = 1.0\text{ MHz}$	-	760	-	pF
$C_{oss}$	Output Capacitance		-	100	-	
$C_{rss}$	Reverse Transfer Capacitance		-	60	-	
$R_G$	Gate Resistance	$f = 1.0\text{ MHz}$	-	1.2	-	$\Omega$

## SWITCHING CHARACTERISTICS (Note 2)

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 20\text{ V}, I_D = 1\text{ A}$ , $V_{GS} = 10\text{ V}, R_{GS} = 6\ \Omega$	-	9	18	ns
$t_r$	Turn-On Rise Time		-	5	10	
$t_{d(off)}$	Turn-Off Delay Time		-	23	17	
$t_f$	Turn-Off Fall Time		-	3	6	
$Q_g$	Total Gate Charge	$V_{DS} = 20\text{ V}, I_D = 7.6\text{ A}$ , $V_{GS} = 5\text{ V}$	-	7.7	11	nC
$Q_{gs}$	Gate-Source Charge		-	2.4	-	
$Q_{gd}$	Gate-Drain Charge		-	2.8	-	

## DRAIN-SOURCE DIODE CHARACTERISTICS

$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 2.1\text{ A}$ (Note 2)	-	0.76	1.2	V
$t_{rr}$	Diode Reverse Recovery Time	$I_F = 7.6\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}$	-	17	-	ns
$Q_{rr}$	Diode Reverse Recovery Charge		-	7	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

### NOTES:

- $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a)  $50^\circ\text{C}/\text{W}$  when mounted on a 1 in<sup>2</sup> pad of 2 oz. copper.



b)  $125^\circ\text{C}/\text{W}$  when mounted on a minimum pad.

- Pulse Test: Pulse Width < 300  $\mu\text{s}$ , Duty Cycle < 2.0%
- $BV(\text{avalanche})$  Single-Pulse rating is guaranteed if device is operated within the UIS SOA boundary of the device.

TYPICAL CHARACTERISTICS

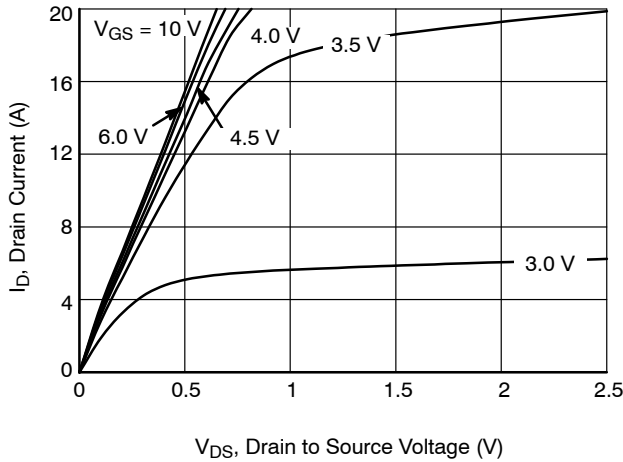


Figure 1. On Region Characteristics

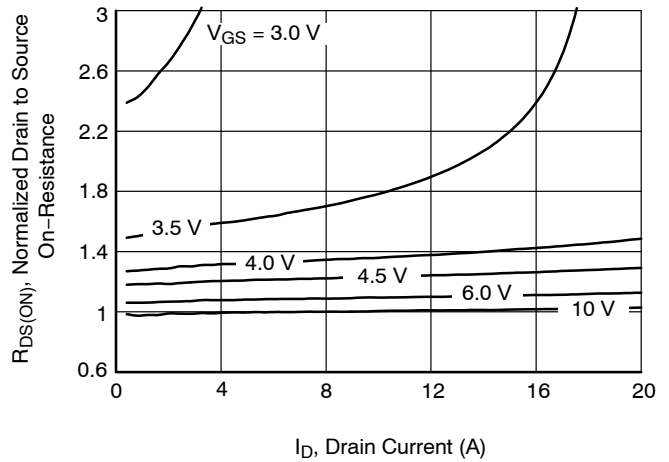


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

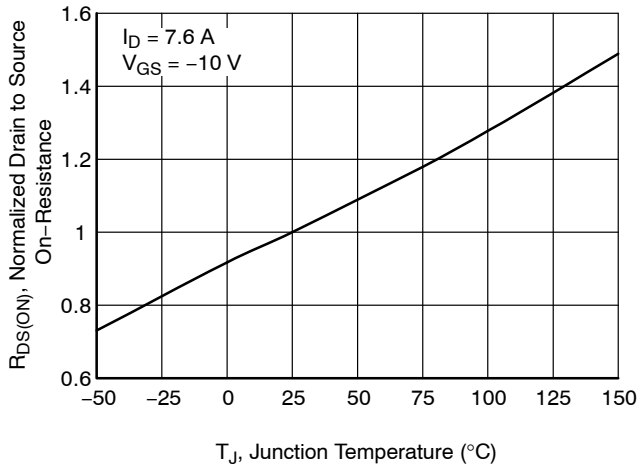


Figure 3. On-Resistance Variation with Temperature

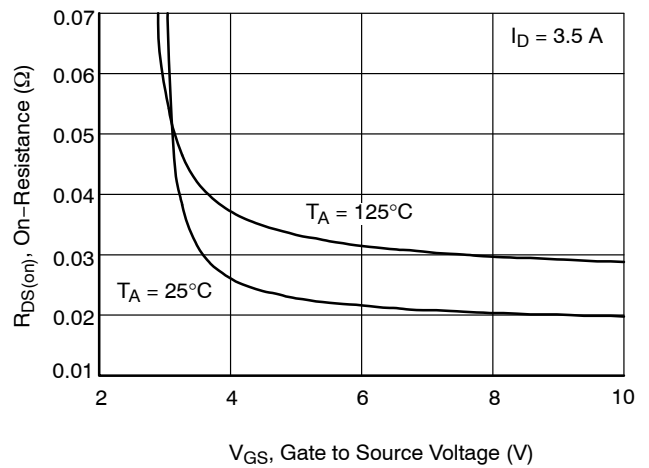


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

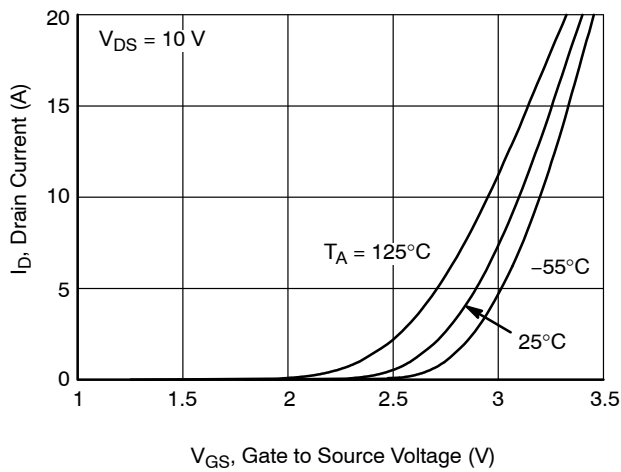


Figure 5. Transfer Characteristics

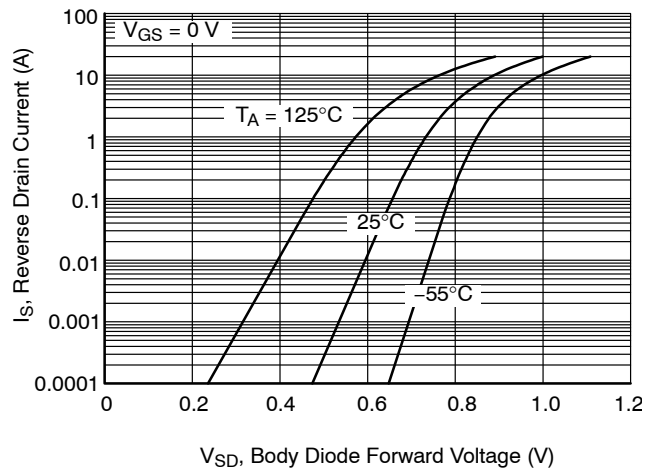


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

TYPICAL CHARACTERISTICS (continued)

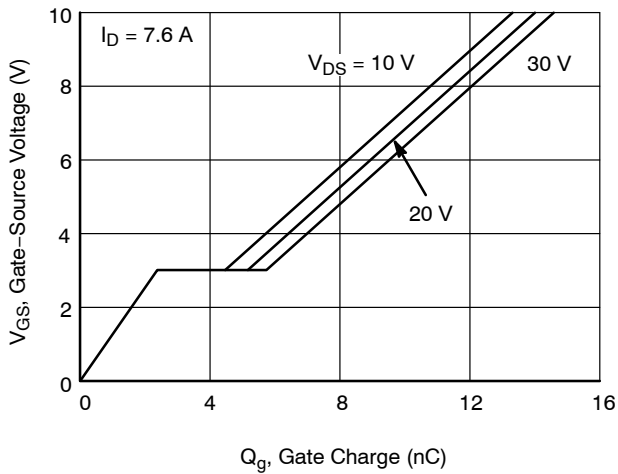


Figure 7. Gate Charge Characteristics

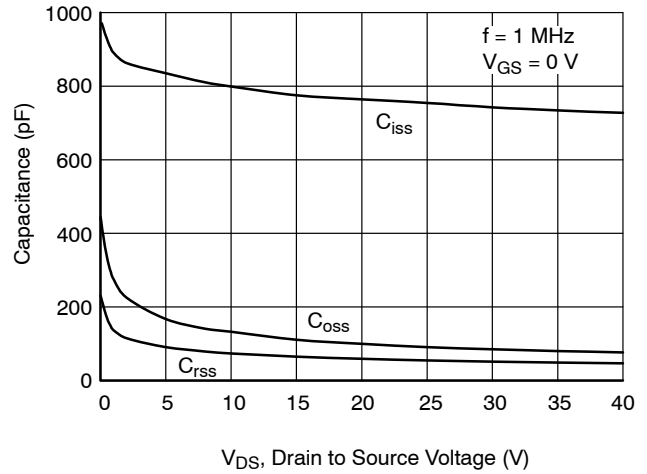


Figure 8. Capacitance Characteristics

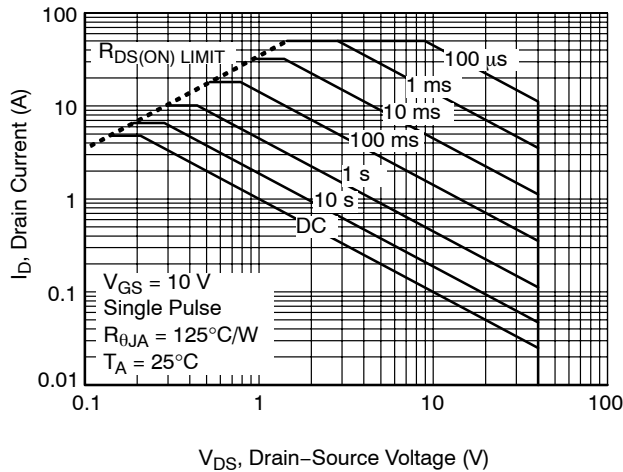


Figure 9. Maximum Safe Operating Area

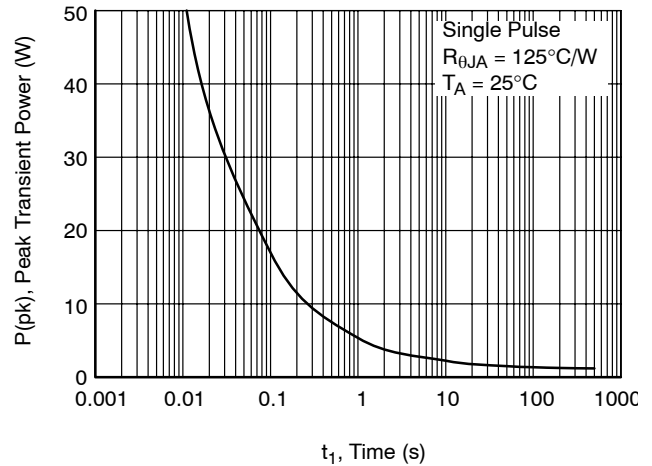


Figure 10. Single Pulse Maximum Power Dissipation

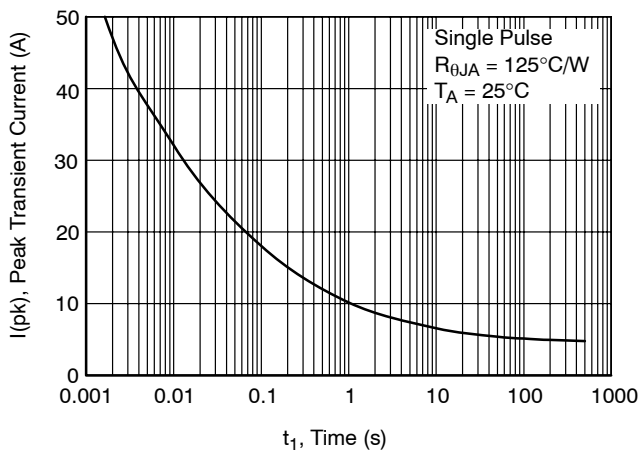


Figure 11. Single Pulse Maximum Peak Current

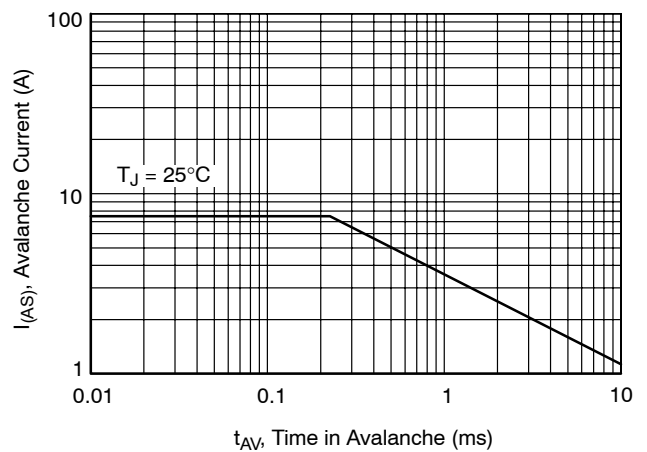
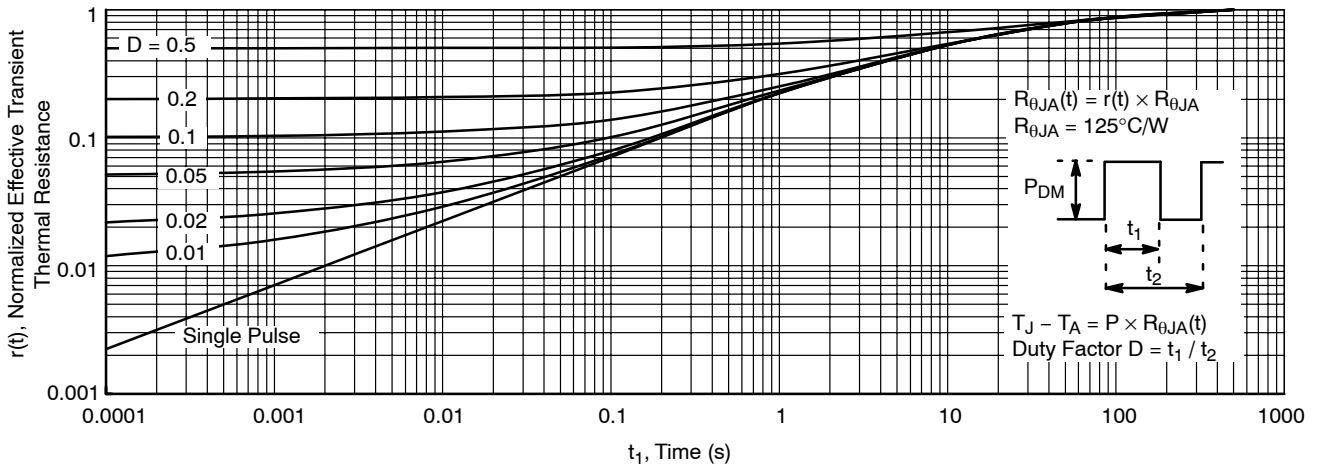


Figure 12. Unclamped Inductive Switching Capability

TYPICAL CHARACTERISTICS (continued)



**Figure 13. Transient Thermal Response Curve**

NOTE: Transient thermal response will change depending on the circuit board design.

# MECHANICAL CASE OUTLINE

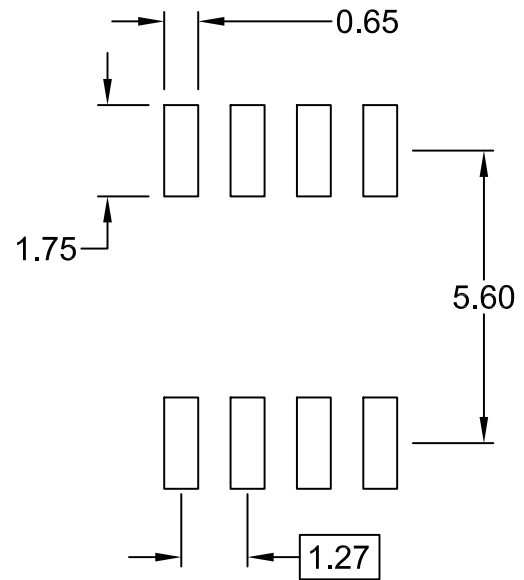
## PACKAGE DIMENSIONS

ON Semiconductor®

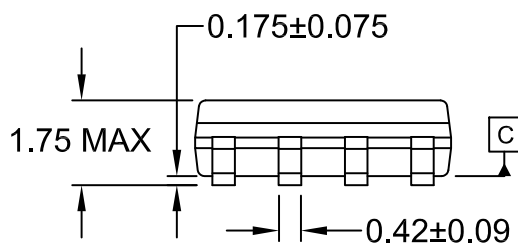


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CASE 751EB  
ISSUE A

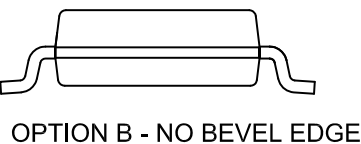
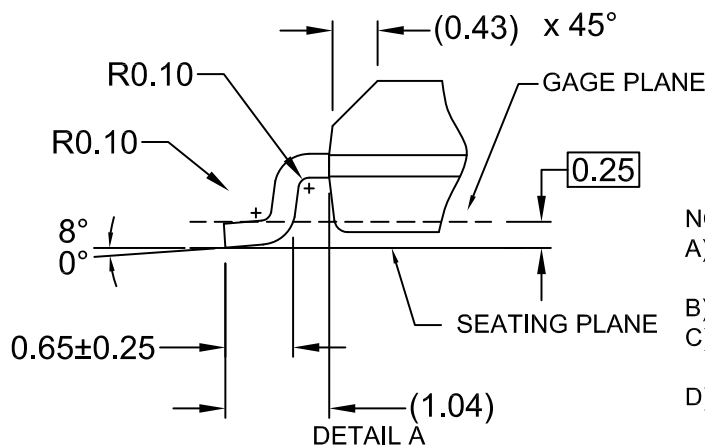
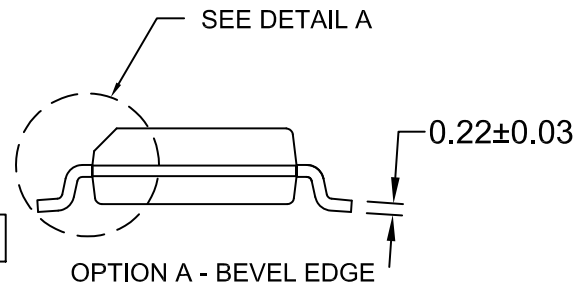
DATE 24 AUG 2017



⊕ 0.25 (M) C B A



⌒ 0.10



NOTES:

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M

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